### Bill of Materials

<table>
<thead>
<tr>
<th>Item</th>
<th>Part</th>
<th>Quantity</th>
<th>Manufacturer</th>
<th>Value</th>
<th>Product name</th>
<th>Description</th>
<th>Package name</th>
<th>Standard dimensions mm (inch)</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>IC1</td>
<td>1</td>
<td>TOSHIBA</td>
<td>-</td>
<td>TCR5BMxxA (*)</td>
<td>Output current 500 mA</td>
<td>DFN5B</td>
<td>1.2×1.2</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td>TCR8BMxxA (*)</td>
<td>Output current 800 mA</td>
<td></td>
<td></td>
</tr>
<tr>
<td>2</td>
<td>C1</td>
<td>1</td>
<td></td>
<td>1 μF</td>
<td>Ceramic 6.3 V ±20 %</td>
<td>-</td>
<td>0.6×0.3 (0201)</td>
<td></td>
</tr>
<tr>
<td>3</td>
<td>C2</td>
<td>1</td>
<td></td>
<td>0.1 μF</td>
<td>Ceramic 6.3 V ±20 %</td>
<td>-</td>
<td>0.6×0.3 (0201)</td>
<td></td>
</tr>
<tr>
<td>4</td>
<td>C3</td>
<td>1</td>
<td></td>
<td>22 μF</td>
<td>Ceramic 10 V ±20 %</td>
<td>-</td>
<td>1.6×0.8 (0603)</td>
<td></td>
</tr>
</tbody>
</table>

* In the bill of materials, the xx part of the product name is a number indicating the output voltage. Ex.) When $V_{OUT}=1.2$ V, TCR5BM12A/TCR8BM12A
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